

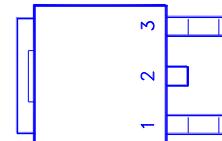
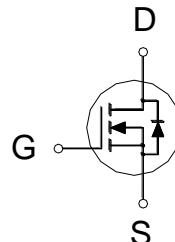
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****PD6A8BA**

TO-252

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
40V	6.2mΩ	75A

**ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ²	$T_C = 25^\circ\text{C}$	I_D	75	A
	$T_C = 100^\circ\text{C}$		47	
Pulsed Drain Current ¹		I_{DM}	120	A
Avalanche Current		I_{AS}	35	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	61.2	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	73	W
	$T_C = 100^\circ\text{C}$		29	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.7	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.²Package limitation current is 55A**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.7	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5\text{V}, I_D = 15\text{A}$		5.5	8	$\text{m}\Omega$
		$V_{GS} = 10\text{V}, I_D = 20\text{A}$		4.9	6.2	

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Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		85		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 20V, f = 1MHz$		2181		pF
Output Capacitance	C_{oss}			261		
Reverse Transfer Capacitance	C_{rss}			152		
Gate Resistance	R_g		$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	1.4		Ω
Total Gate Charge ²	$Q_{g(VGS=10V)}$	$V_{DS} = 20V, I_D = 20A$		42		nC
	$Q_{g(VGS=4.5V)}$			22		
Gate-Source Charge ²	Q_{gs}			5.7		
Gate-Drain Charge ²	Q_{gd}			10		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 20V$ $I_D \approx 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$		19		nS
Rise Time ²	t_r			12		
Turn-Off Delay Time ²	$t_{d(off)}$			58		
Fall Time ²	t_f			10		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S			56		A
Forward Voltage ¹	V_{SD}	$I_F = 20A, V_{GS} = 0V$		1.3		V
Reverse Recovery Time	t_{rr}	$I_F = 20A, dI_F/dt = 100A / \mu S$		16		nS
Reverse Recovery Charge	Q_{rr}			5		nC

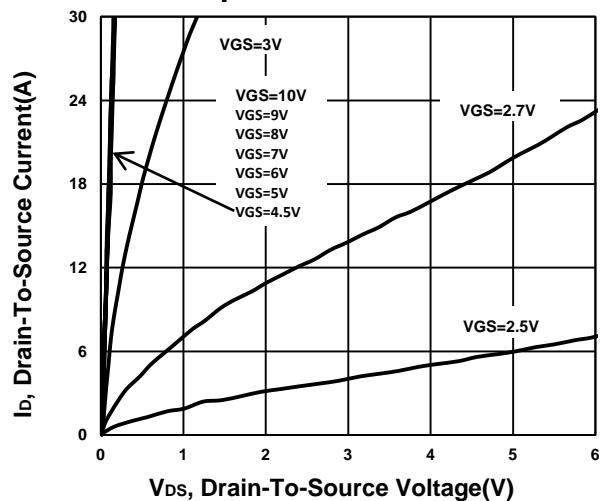
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Package limitation current is 55A

NIKO-SEM

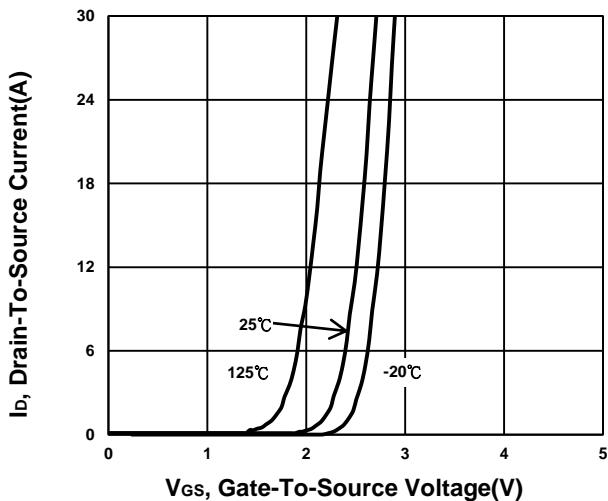
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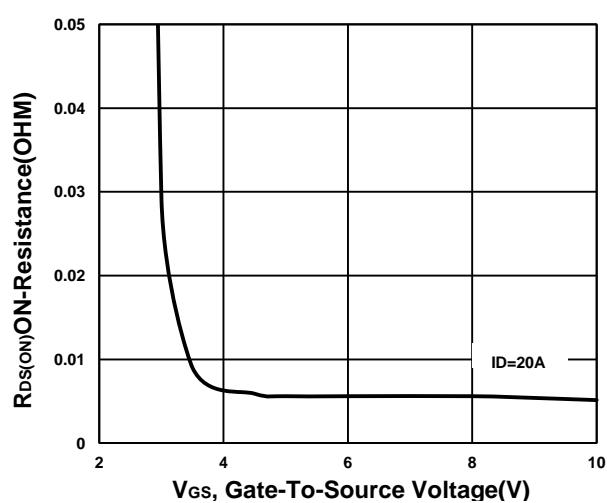
Output Characteristics



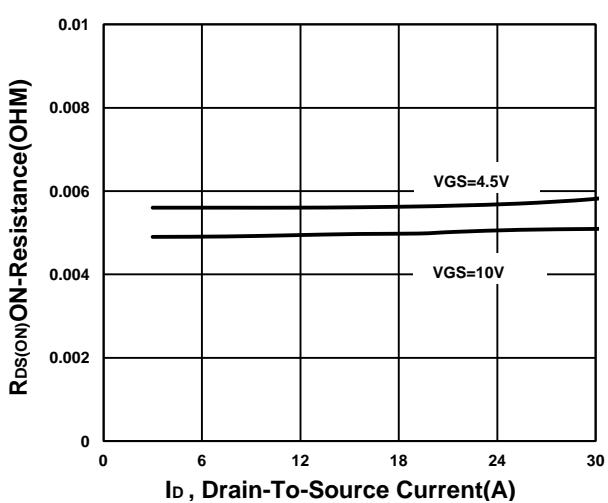
Transfer Characteristics



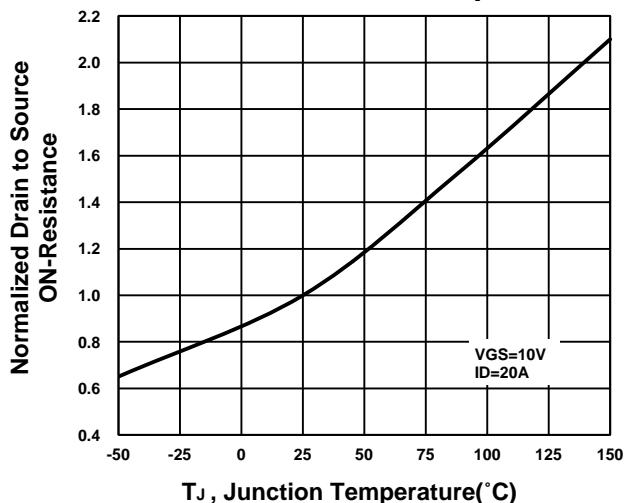
On-Resistance VS Gate-To-Source



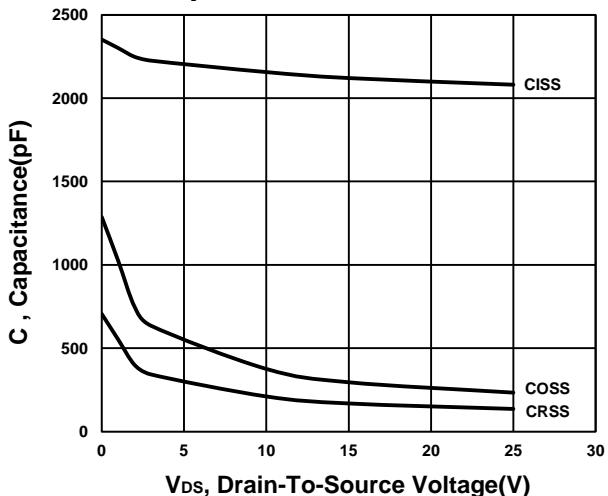
On-Resistance VS Drain Current



On-Resistance VS Temperature



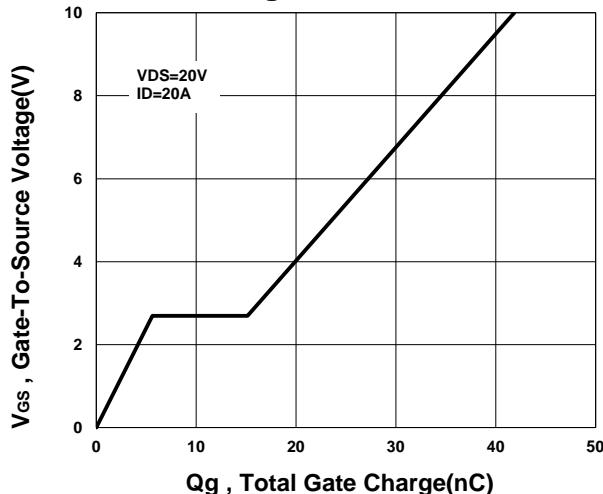
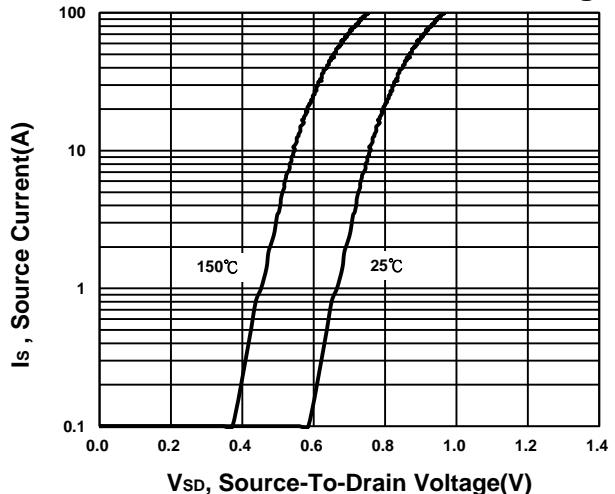
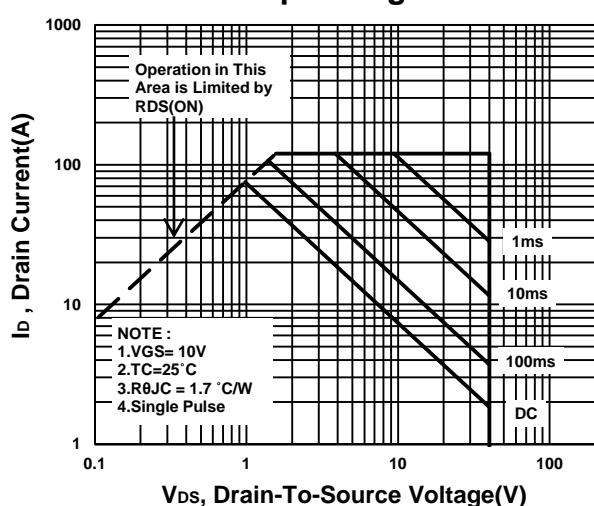
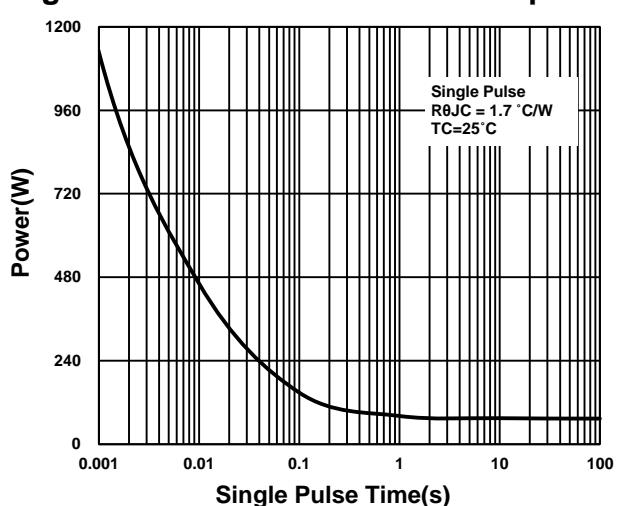
Capacitance Characteristic



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Gate charge Characteristics**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**